

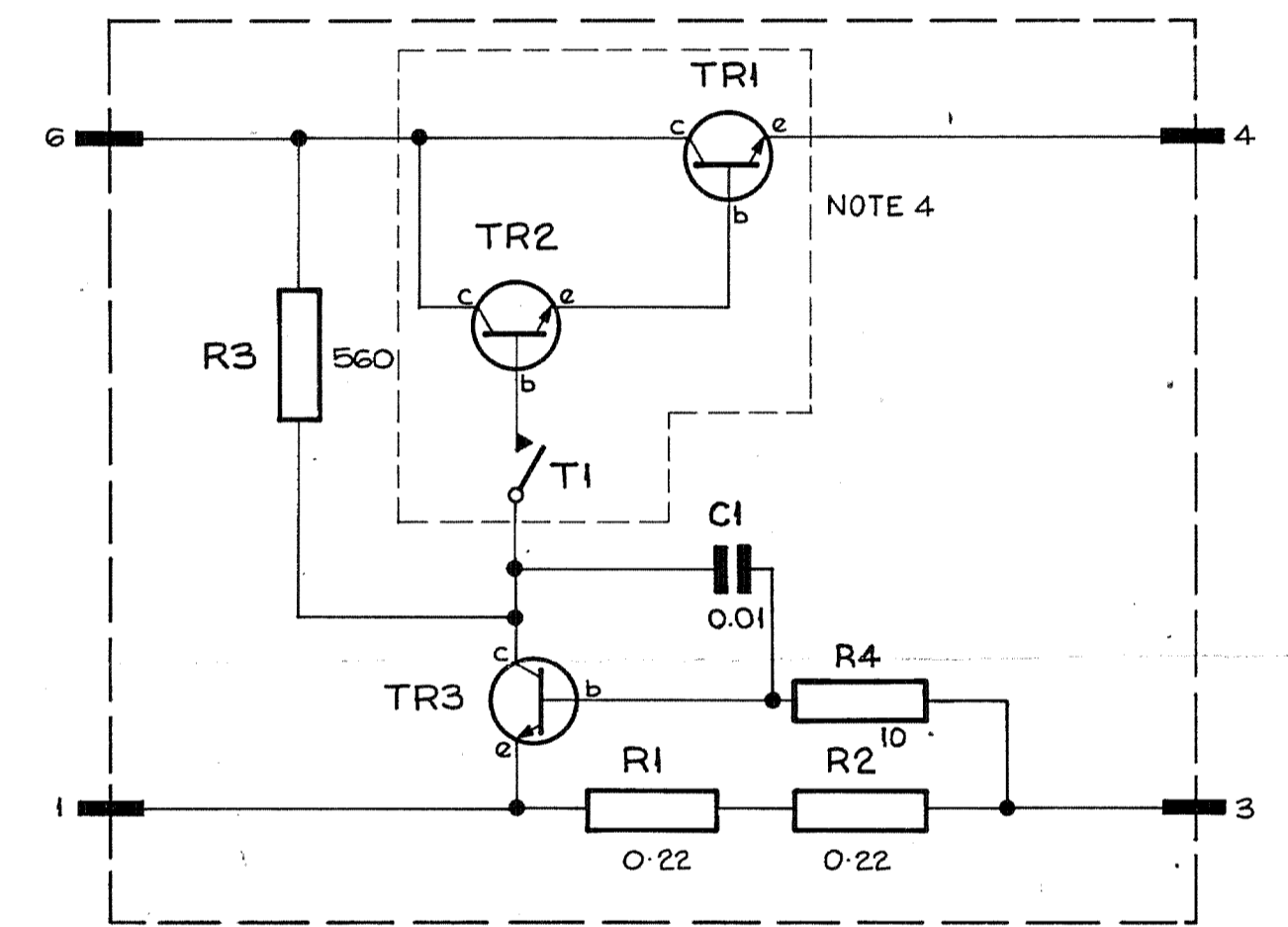
PC BOARD DETAILS

PRINTED CIRCUIT BOARD NEGATIVES & SILK SCREEN AVAILABLE FROM ELECTRICAL-MECHANICAL SECTION, E-IN-C WELLINGTON.
PRINTED CIRCUIT BOARD TO BE MADE FROM 1.6mm THICK G10 FIBREGLASS, 70 MICRON COPPER SINGLE SIDED.

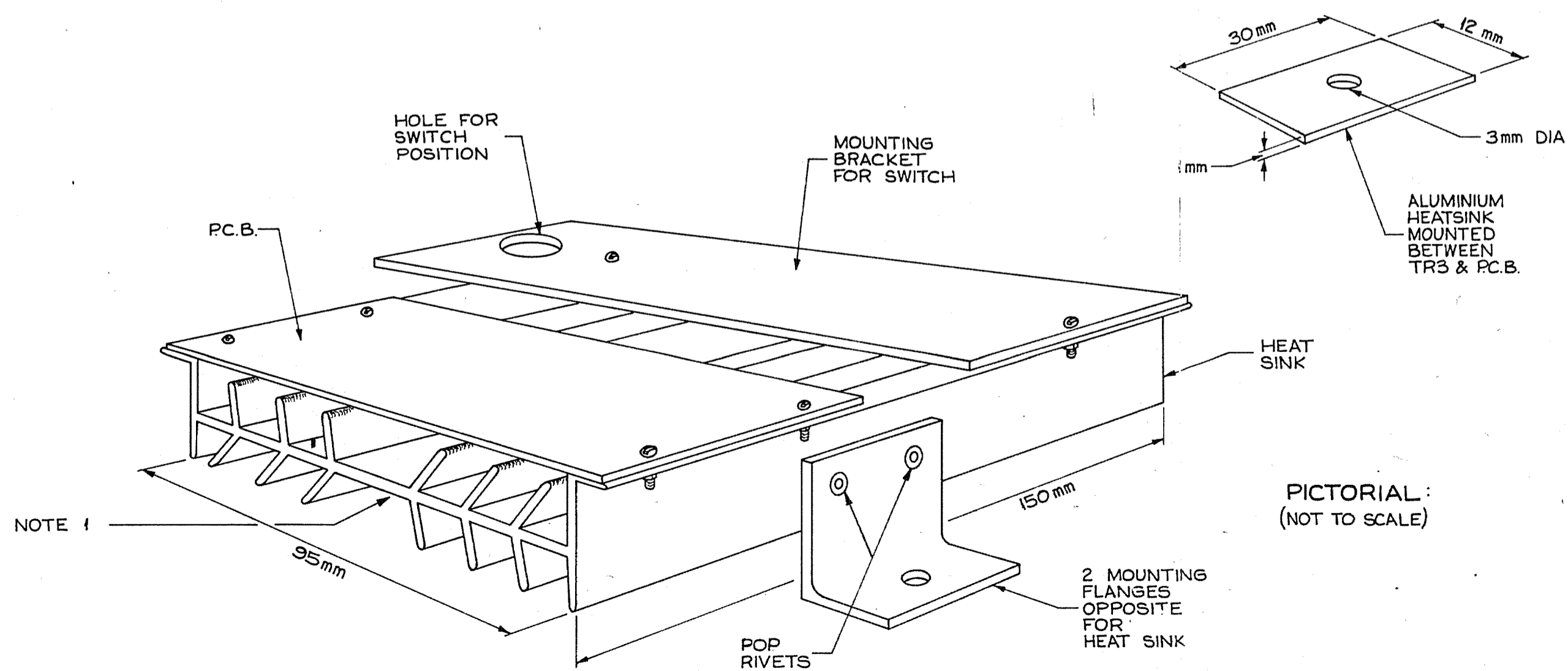
DRILLING DETAILS

ALL PRINTED CIRCUIT BOARD DRILLINGS ARE TO BE 1.2mm EXCEPT THE INDICATED HOLES BELOW.
A - 3mm DIA

COMPONENT LIST					
PART	DESCRIPTION	VALUE	RATING	PART N ^o	NOTES
R1, 2	RESISTOR	0.22	2W		WIRE WOUND
R3	RESISTOR	560	5W		WIRE WOUND
C1	CAPACITOR	0.01	100V		
TR1	TRANSISTOR			2N3772	RCA
TR2	TRANSISTOR			TIP49	
TR3	TRANSISTOR			TIP49	
T1	MICROTHERM	80°C			INSULATED, NZ SOLENOID OR SIMILAR
	MOLEX CONNECTOR			M3003-6	FEMALE CONN. M3011-6-1/2
R4	RESISTER	10	1/4 W	SL ER 201	



SCHEMATIC



NOT TO BE USED FOR NEW WORK
SEE DRAWING 42397 SHT. 3

NOTES:

1. THE MICROTHERM IS TO BE MOUNTED ON THE CASE OF TRANSISTOR TR1 WHICH IS MOUNTED ON THE UNDERSIDE OF HEATSINK.
2. THE HEATSINK IS TO BE 150mm LONG AND HAVE A THERMAL RATING OF NOT GREATER THAN 2°C/WATT
3. THE HEATSINK AND ALUMINIUM BRACKETS SHALL BE PAINTED MATT BLACK
4. MOUNTED ON HEATSINK

CONVERTER CURRENT LIMIT						N Z P O	
DEL	CKD	APD	ORDER	DATE	ISS	CHANGE	
PE	DN	GC	155428	20.5.77	A	ENGINEER-IN-CHIEF, WELLINGTON	
KMJ	DG	CWS	17346	9.2.78	B	NOTES 2 & 4 ADDED	
NMP	AB	GC	4306	1.11.78	C	R4 ADDED	
IPP	PBC	PBC	20969	6.2.80	F	DRAWING SUPERCEDED.	
						COY N ^o	ORIGIN: EM
						1 OF 1	DRAWN: EM TRACED: PE.
						A2	40979